# 6-534998-3 ACTIVE

#### AMPMODU | Modu Connector System

TE Internal #: 6-534998-3

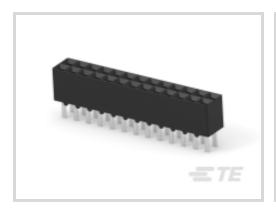
PCB Mount Receptacle, Vertical, Board-to-Board, 26 Position, 2.54 mm [.1 in] Centerline, Gold, Through Hole - Solder, Signal, Modu

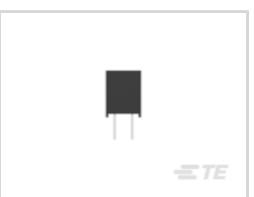
Connector System

View on TE.com >

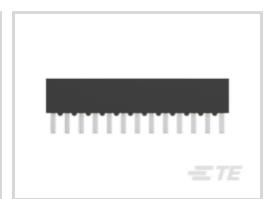


Connectors > PCB Connectors > PCB Headers & Receptacles











PCB Connector Assembly Type: PCB Mount Receptacle

PCB Mount Orientation: Vertical
Connector System: Board-to-Board

Number of Positions: 26
Number of Rows: 2

## **Features**

### **Product Type Features**

Applied Pressure	Standard
PCB Connector Assembly Type	PCB Mount Receptacle
Connector System	Board-to-Board
Sealable	No
Connector & Contact Terminates To	Printed Circuit Board
Configuration Features	

Stackable	Yes
PCB Mount Orientation	Vertical
Number of Positions	26
Number of Rows	2
Board-to-Board Configuration	Parallel

#### **Electrical Characteristics**

Dielectric Withstanding Voltage (Max)	750 VAC
Insulation Resistance	5000 ΜΩ



Operating Voltage	333 VAC
Body Features	
Connector Profile	Low
Primary Product Color	Black
Contact Features	
Contact Protection Type	Closed Entry Housing
Contact Mating Area Length	3.77 mm[.148 in]
Mating Square Post Dimension	.64 mm[.025 in]
PCB Contact Termination Area Plating Material Thickness	3.81 – 7.61 μm
Contact Shape & Form	Round
PCB Contact Termination Area Plating Material	Tin
Contact Base Material	Phosphor Bronze
Contact Mating Area Plating Material	Gold
Contact Mating Area Plating Material Thickness	.762 μm[30 μin]
Contact Type	Socket
Contact Current Rating (Max)	2 A
Termination Features	
Rectangular Termination Post & Tail Thickness	.2 mm[.008 in]
Rectangular Termination Post & Tail Width	.7 mm[.028 in]
Termination Post & Tail Length	3.18 mm[.125 in]
Termination Method to Printed Circuit Board	Through Hole - Solder
Mechanical Attachment	
Mating Alignment	Without
PCB Mount Retention	Without
PCB Mount Alignment	Without
Connector Mounting Type	Board Mount
Housing Features	
Mating Entry Location	Тор
Centerline (Pitch)	2.54 mm[.1 in]
Housing Material	Thermoplastic
Dimensions	
Connector Height	5.03 mm[.198 in]



Row-to-Row Spacing	2.54 mm[.1 in]
Stack Height	9.02 mm[.355 in]
PCB Thickness (Recommended)	1.57 mm[.055 – .094 in]
Usage Conditions	
Housing Temperature Rating	Standard
Operating Temperature Range	-65 – 125 °C[-85 – 257 °F]
Operation/Application	
Solder Process Feature	Board Standoff
Circuit Application	Signal
Industry Standards	
Approved Standards	CSA LR7189, UL E28476
UL Flammability Rating	UL 94V-0
Packaging Features	

17

Box, Tube

### **Product Compliance**

Packaging Quantity

Packaging Type

For compliance documentation, visit the product page on TE.com>

EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JUNE 2023 (235) Candidate List Declared Against: JAN 2022 (223) Does not contain REACH SVHC
Halogen Content	Not Low Halogen - contains Br or Cl > 900 ppm.
Solder Process Capability	Wave solder capable to 265°C

#### Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous

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materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-on-reach

# Compatible Parts



# Also in the Series | Modu Connector System



Automotive Housings(2)



Board-to-Board Jumpers & Shunts(5)



PCB Connector Covers(4)



PCB Connector Keying(4)



PCB Headers & Receptacles(1245)



# Customers Also Bought









PCB Mount Receptacle, Vertical, Board-to-Board, 26 Position, 2.54 mm [.1 in] Centerline, Gold, Through Hole - Solder, Signal, Modu Connector System





TE Part #6274359-1 JACK, VERT,PCB,75 OHM,BNC TE Part #1SNS420135Z0001 AND0003148873-A (BN10-ABT) TE Part #1SNS420136Z0001 AN00003166739-A (BN47-AEQS AN00003166739 TE Part #1SNS420246Z0000 AN00003102952-A (XT08+BDA)

TE Part #1SNS420340Z0000 NRD0000758433-A (XT03\_MV NR00000758431)

### **Documents**

#### **Product Drawings**

26 MODIV VRT DR CE 100/125

English

### **CAD Files**

**Customer View Model** 

ENG\_CVM\_CVM\_6-534998-3\_R.2d\_dxf.zip

English

3D PDF

3D

**Customer View Model** 

ENG\_CVM\_CVM\_6-534998-3\_R.3d\_igs.zip

English

**Customer View Model** 

ENG\_CVM\_CVM\_6-534998-3\_R.3d\_stp.zip

English

By downloading the CAD file I accept and agree to the **Terms and Conditions** of use.

## Datasheets & Catalog Pages

AMPMODU\_INTERCONNECTION\_SYSTEM\_SECTION5

English

## **Product Specifications**

**Application Specification** 

English